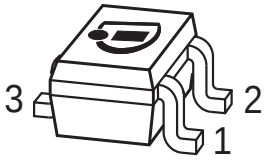
NPN Silicon RF Transistor*



- For broadband amplifiers up to 2 GHz and fast non-saturated switches at collector currents from 0.5 mA to 20 mA
- Complementary type: BFT92W (PNP)
- Pb-free (RoHS compliant) package [1)]
- Qualified according AEC Q101

* Short term description

AEC Qualified RoHS

ESD (**E**lectro**s**tatic **d**ischarge) sensitive device, observe handling precaution!

Type	Marking	Pin Configuration			Package
BFR92W	P1s	1=B	2=E	3=C	SOT323

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CEO}	15	V
Collector-emitter voltage	V_{CES}	20	
Collector-base voltage	V_{CBO}	20	
Emitter-base voltage	V_{EBO}	2.5	
Collector current	I_C	45	mA
Base current	I_B	4	
Total power dissipation[2)] $T_S \leq 86$ °C	P_{tot}	280	mW
Junction temperature	T_j	150	°C
Ambient temperature	T_A	-65 ... 150	
Storage temperature	T_{stg}	-65 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point[3)]	R_{thJS}	≤ 230	K/W

[1]Pb-containing package may be available upon special request

[2]T_S is measured on the collector lead at the soldering point to the pcb

[3]For calculation of R_{thJA} please refer to Application Note Thermal Resistance

Electrical Characteristics at T_A = 25°C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage I_C = 1 mA, I_B = 0	$V_{(BR)CEO}$	15	-	-	V
Collector-emitter cutoff current V_{CE} = 20 V, V_{BE} = 0	I_{CES}	-	-	10	µA
Collector-base cutoff current V_{CB} = 10 V, I_E = 0	I_{CBO}	-	-	100	nA
Emitter-base cutoff current V_{EB} = 2.5 V, I_C = 0	I_{EBO}	-	-	100	µA
DC current gain- I_C = 15 mA, V_{CE} = 8 V, pulse measured	h_{FE}	70	100	140	-

Electrical Characteristics at T_A = 25°C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics (verified by random sampling)					
Transition frequency I_C = 15 mA, V_{CE} = 8 V, f = 500 MHz	f_T	3.5	5	-	GHz
Collector-base capacitance V_{CB} = 10 V, f = 1 MHz, V_{BE} = 0 , emitter grounded	C_{cb}	-	0.42	0.6	pF
Collector emitter capacitance V_{CE} = 10 V, f = 1 MHz, V_{BE} = 0 , base grounded	C_{ce}	-	0.27	-	
Emitter-base capacitance V_{EB} = 0.5 V, f = 1 MHz, V_{CB} = 0 , collector grounded	C_{eb}	-	0.66	-	
Noise figure I_C = 2 mA, V_{CE} = 6 V, Z_S = Z_{Sopt}, f = 900 MHz I_C = 2 mA, V_{CE} = 6 V, Z_S = Z_{Sopt}, f = 1.8 GHz	F	 - -	 1.4 2	 - -	dB
Power gain, maximum available[1)] I_C = 15 mA, V_{CE} = 8 V, Z_S = Z_{Sopt}, Z_L = Z_{Lopt} , f = 900 MHz I_C = 15 mA, V_{CE} = 8 V, Z_S = Z_{Sopt}, Z_L = Z_{Lopt}, f = 1.8 GHz	G_{ma}	 - -	 17 11.5	 - -	
Transducer gain I_C = 15 mA, V_{CE} = 8 V, Z_S = Z_L = 50 Ω, f = 900 MHz I_C = 15 mA, V_{CE} = 8 V, Z_S = Z_L = 50 Ω, f = 1.8 MHz	$\lvert S_{21e}\rvert^2$	 - -	 13.5 8	 - -	dB

[1] $G_{ma} = |S_{21e} / S_{12e}| (k-(k^2-1)^{1/2})$

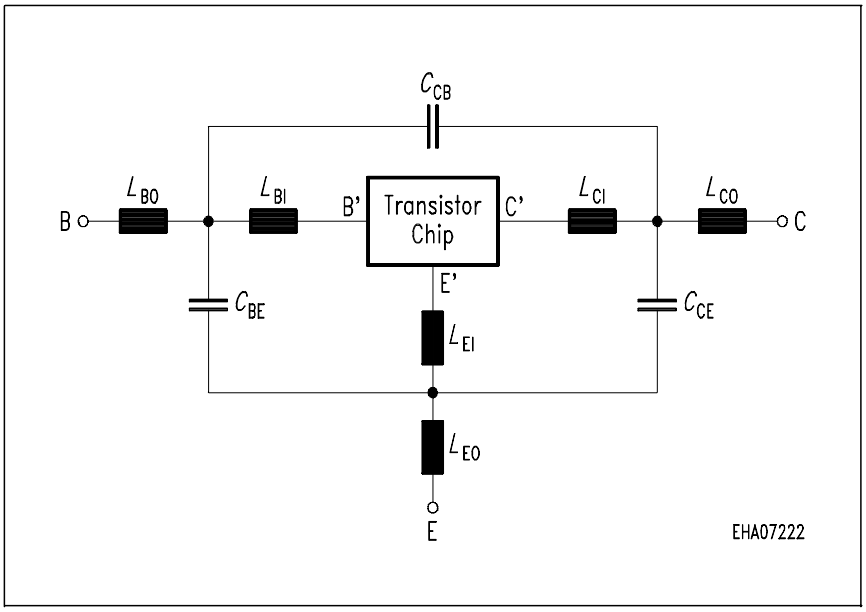
SPICE Parameter (Gummel-Poon Model, Berkley-SPICE 2G.6 Syntax):

Transistor Chip Data:

IS =	0.1213	fA	BF =	94.733	-	NF =	1.0947	-
VAF =	30	V	IKF =	0.46227	A	ISE =	129.55	fA
NE =	1.9052	-	BR =	10.729	-	NR =	0.8983	-
VAR =	14.599	V	IKR =	0.01	A	ISC =	0.75557	fA
NC =	1.371	-	RB =	14.998	Ω	IRB =	0.01652	mA
RBM =	7.8145	Ω	RE =	0.29088	-	RC =	0.13793	Ω
CJE =	10.416	fF	VJE =	0.70618	V	MJE =	0.34686	-
TF =	26.796	ps	XTF =	0.3817	-	VTF =	0.32861	V
ITF =	4.4601	mA	PTF =	0	deg	CJC =	946.47	fF
VJC =	0.84079	V	MJC =	0.4085	-	XCJC =	0.13464	-
TR =	1.2744	ns	CJS =	0	fF	VJS =	0.75	V
MJS =	0	-	XTB =	0	-	EG =	1.11	eV
XTI =	3	-	FC =	0.99545		TNOM	300	K

All parameters are ready to use, no scalling is necessary. Extracted on behalf of Infineon Technologies AG by: Institut für Mobil- und Satellitentechnik (IMST)

Package Equivalent Circuit:

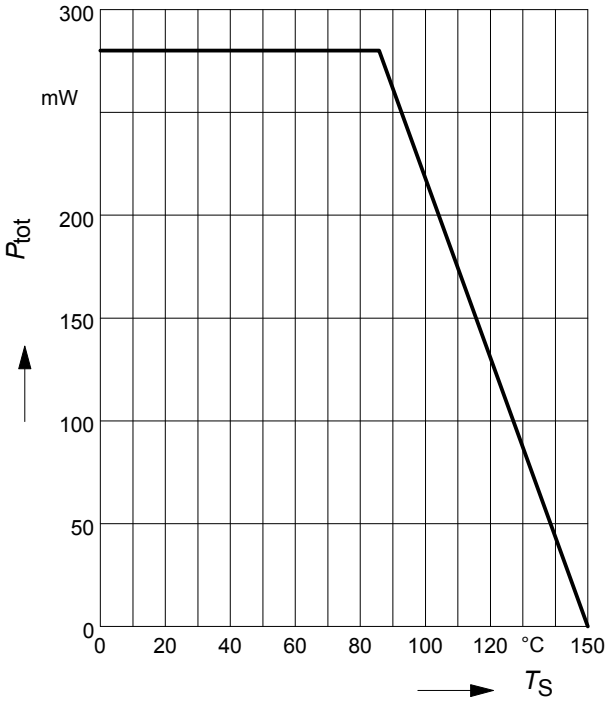


L_{BI} =	0.57	nH
L_{BO} =	0.4	nH
L_{EI} =	0.43	nH
L_{EO} =	0.5	nH
L_{CI} =	0	nH
L_{CO} =	0.41	nH
C_{BE} =	61	fF
C_{CB} =	101	fF
C_{CE} =	175	fF

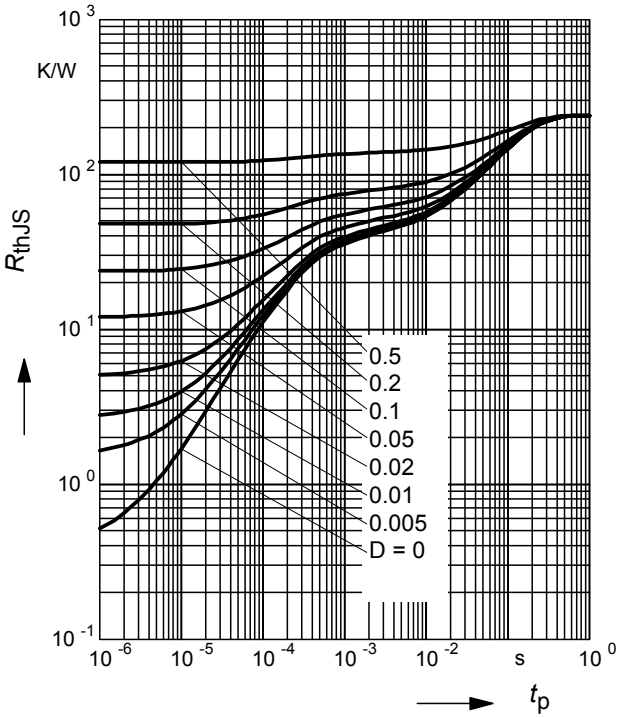
Valid up to 6GHz

For examples and ready to use parameters please contact your local Infineon Technologies distributor or sales office to obtain a Infineon Technologies CD-ROM or see Internet: http://www.infineon.com

Total power dissipation $P_{tot} = f(T_S)$

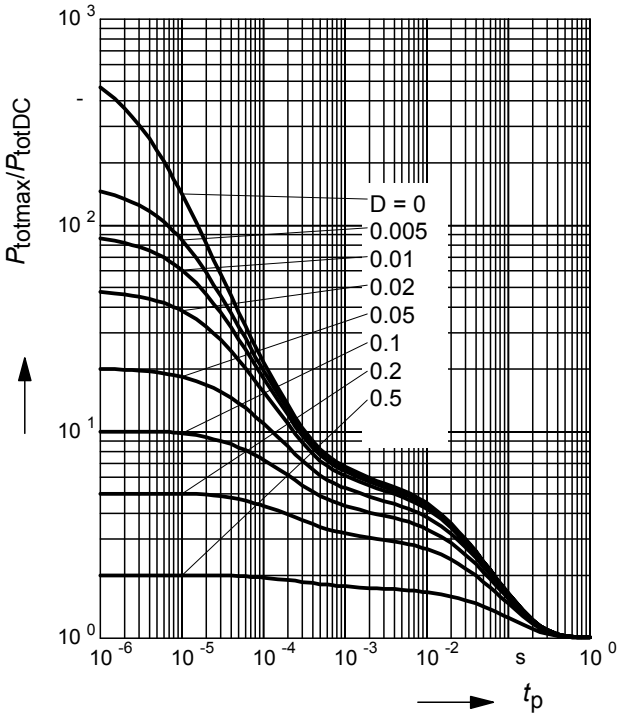


Permissible Pulse Load $R_{thJS} = f(t_p)$

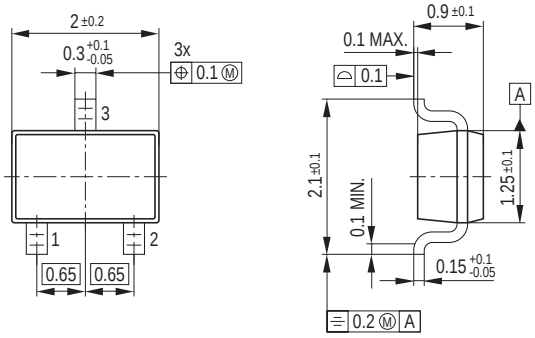


Permissible Pulse Load

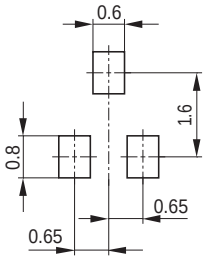
$P_{totmax}/P_{totDC} = f(t_p)$



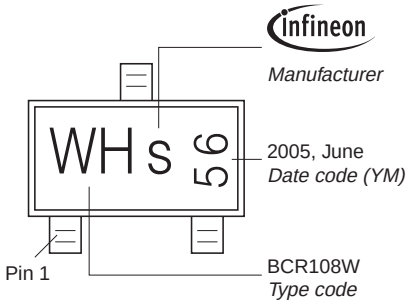
Package Outline



Foot Print

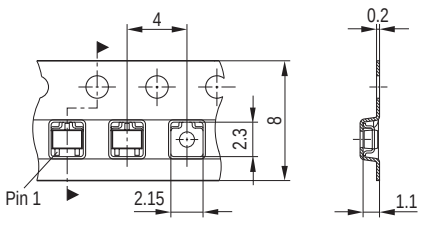


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel



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